Our partner



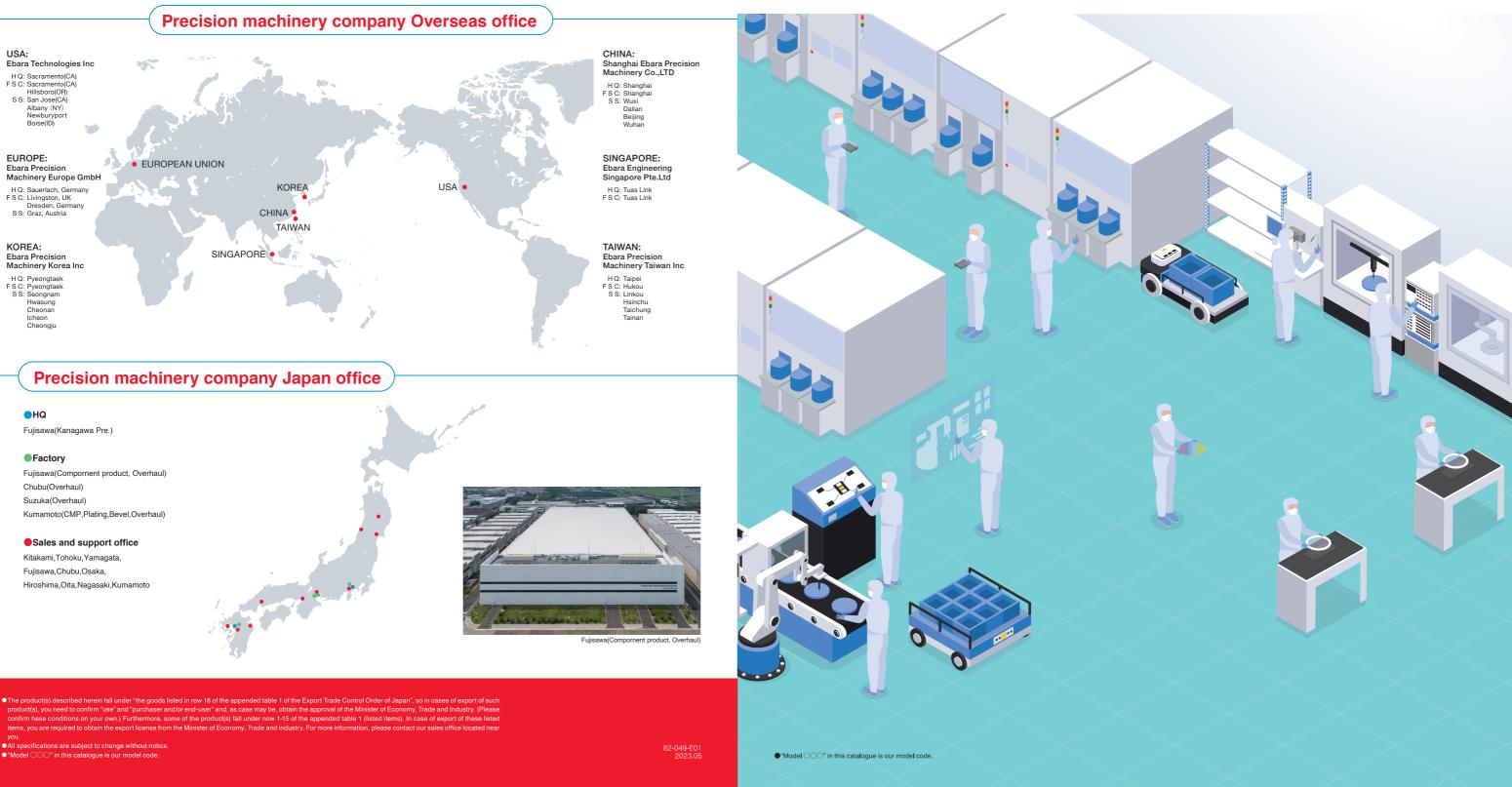
Precision machinery company

4-2-1 Honfujisawa, Fujisawa-shi Kanagawa 251-8502, Japan TEL 81-466-83-8111 https://www.ebara.co.jp/en/





Point of use abatement systems **Combustion type Model TND, G5, G6**



Ahead > Beyond

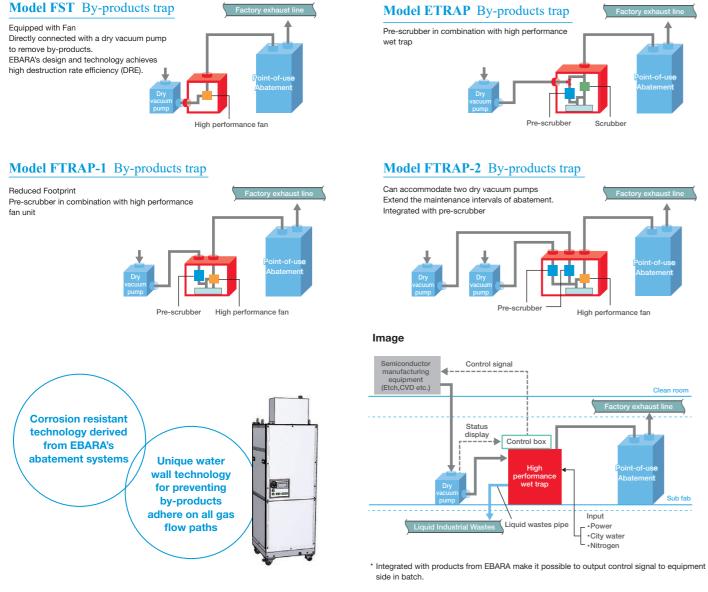
High performance wet trap Model FST, ETRAP, FTRAP



High performance wet trap Model FST, ETRAP, FTRAP

High performance wet trap installed behind a dry vacuum pump for extending the maintenance intervals of abatement system. Simple structure helps maintaining process uptime. Integrated with EBARA combustion type abatement, wet trap model can be applied for the wide range of semiconductor process.

Image



-A4

TND-Double

TND-Dual

800

800

800

 ~ 4

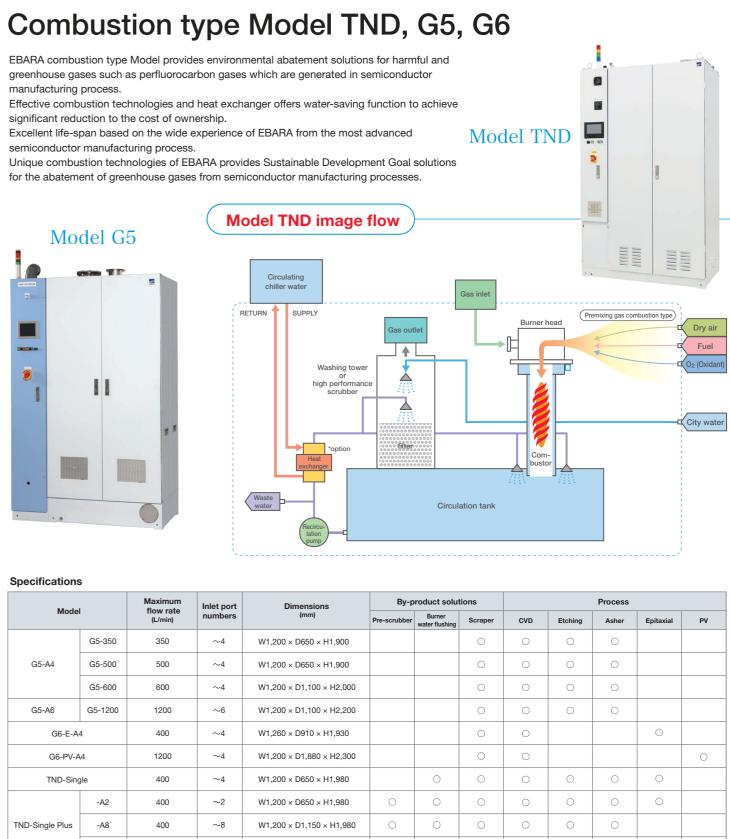
 $\sim 4+4$

 $\sim 6+6$

W1,600 × D850 × H1,980

W1,800 × D650 × H1,980

W1,860 × D750 × H1,980



Specifications

Model	Maximum flow rate (L/min)	Inlet port numbers	Dimensions (mm)	Technology		Process							
				Washing Tower	mance	CVD		Etching		Asher	Epitaxial	Feature	
						SiO2 (HCD/DCS)	TiO₂ (TiCl₄)	WO3 (WF6)	SiO2 (SiF4)	B2O3 (BCl3)	NH ₃	SiO ₂ (DCS)	
FST	400	1	W400 × D390 × H1,026		0	0	0				0	0	Directly connected with a dry vacuum pump
ETRAP	400	1	W640 × D640 × H1,980	0		0	0	0	0	0	0	0	Low cost type
FTRAP-1	180	1	W900 × D700 × H1,980		0	0	0	0	0	0	0	0	High DRE
FTRAP-2	360	2	W900 × D700 × H1,980		0	0	0	0	0	0	0	0	High DRE

*Install an appropriate abatement after the high performance wet trap *Please contact us for details.

*If you are considering other than semiconductor manufacturing process, please contact us.

Ву-р	roduct solut	tions	Process									
Pre-scrubber	Burner water flushing Scraper		CVD	Etching	Asher	Epitaxial	PV					
		0	0	0	0							
		0	0	0	0							
		0	0	0	0							
		0	0	0	0							
		0	0			0						
		0	0				0					
	0	0	0	0	0	0						
0	0	0	0	0	0	0						
0	0	0	0	0	0							
0	0	0	0	0	0							
	0	0	0	0	0	0						
	0	0	0	0	0	0						